

ABSTRACT OF THE DISCLOSURE

INJECTION MOLD FOR AN OPTICAL SEMICONDUCTOR PACKAGE
AND CORRESPONDING OPTICAL SEMICONDUCTOR PACKAGE

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An injection mold is provided for encapsulating an integrated circuit chip to form a semiconductor package. The injection mold includes at least one injection cavity for housing the chip, and an insert having a front part that forms part of the wall of the injection cavity. A transverse surface of the insert has a roughness that is chosen such that the face of the semiconductor package has a suitable roughness in a corresponding region. Also provided is a semiconductor package that includes an encapsulation block and an integrated circuit chip. The material of the encapsulation block is transparent. One face of the chip includes an optical sensor and lies parallel to a transverse face of the encapsulation block. The transverse face of the encapsulation block includes a region that has a roughness that is less than the roughness of at least the rest of the transverse face.

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